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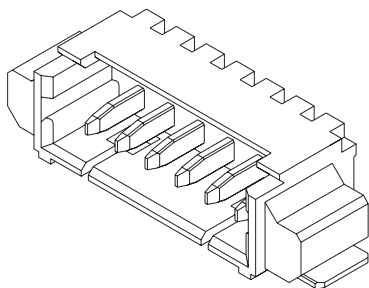
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Jameco Part Number 1932547

1.25mm (.049") Pitch PicoBlade™ Wire-to-Board Header

53261
Right Angle, SMT



Features and Benefits

- Sizes 2 to 15 circuits
- Locking windows provide secure mating
- Metal solder tabs provide PCB hold-down and strain relief for SMT tails

Reference Information

Packaging: Embossed tape
UL File No.: E29179
CSA File No.: LR19980
Mates With: 51021
Designed In: Millimeters

Electrical

Voltage: 125V
Current: 1.0A (32 AWG—0.8A)
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 250V AC/1 min.
Insulation Resistance: 100 Megohms min.

Physical

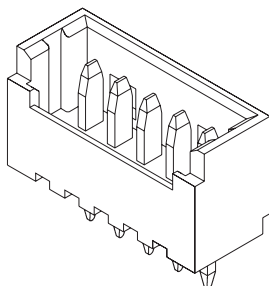
Housing: 4/6 nylon, UL 94V-0
Contact: Phosphor Bronze
Plating: Tin
Solder Tabs: Phosphor Bronze, Tin plating
Operating Temperature: -40 to +85°C

Circuits	Order No.	Carrier Tape Width	Lead-free
2	53261-0271	16.00 (.630)	Yes
3	53261-0371		
4	53261-0471		
5	53261-0571	24.00 (.945)	
6	53261-0671		
7	53261-0771		
8	53261-0871		
9	53261-0971		
10	53261-1071		

Circuits	Order No.	Carrier Tape Width	Lead-free
11	53261-1171	32.00 (1.260)	Yes
12	53261-1271		
14	53261-1471	44.00 (1.732)	
15	53261-1571		

1.25mm (.049") Pitch PicoBlade™ Wire-to-Board Header

53047
Vertical



Features and Benefits

- Sizes 2 to 15 circuits
- Locking windows provide secure mating

Reference Information

Packaging: Tray
Mates With: 51021
Designed In: Millimeters

Electrical

Voltage: 125V
Current: 1.0A (32 AWG—0.8A)
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 250V AC/1 min.
Insulation Resistance: 100 Megohms min.

Physical

Housing: 6/6 nylon, UL 94V-0
Contact: Phosphor Bronze
Plating: Tin
Operating Temperature: -40 to +85°C

Circuits	Order No.	Lead-free
2	53047-0210	Yes
3	53047-0310	
4	53047-0410	
5	53047-0510	
6	53047-0610	
7	53047-0710	
8	53047-0810	

Circuits	Order No.	Lead-free
9	53047-0910	Yes
10	53047-1010	
11	53047-1110	
12	53047-1210	
13	53047-1310	
14	53047-1410	
15	53047-1510	



PRODUCT SPECIFICATION



LANGUAGE

JAPANESE
ENGLISH

[1. 適用範囲 SCOPE]

本仕様書は、
殿に納入する

1.25mmピッチ SMT基板用 コネクタ について規定する。

This specification covers the 1.25mm PITCH WIRE TO BOARD CONNECTOR series.

[2. 製品名称及び型番 PRODUCT NAME AND PART NUMBER]

製品名称 Product Name		製品型番 Part Number
ターミナル Male Terminal (AWG #26-28)	無鉛 LEAD FREE	50079-8*00
ターミナル Male Terminal (AWG #28-32)	無鉛 LEAD FREE	50058-8*00
ハウジング Housing	無鉛 LEAD FREE	51021-**00
ウェハー アッセンブリ Wafer Assembly (R/A)	無鉛 LEAD FREE	53261-**19
ウェハー アッセンブリ Wafer Assembly (R/A)	無鉛 LEAD FREE	53261-**71 (エンボステープ入り Embossed Tape Package)
ウェハー アッセンブリ Wafer Assembly (ST.)	無鉛 LEAD FREE	53398-**19
ウェハー アッセンブリ Wafer Assembly (ST.)	無鉛 LEAD FREE	53398-**71 (エンボステープ入り Embossed Tape Package)

*: 図面参照 Refer to the drawing.

[3. 定格及び適用電線 RATINGS AND APPLICABLE WIRES]

項目 Item	規格 Standard	
最大許容電圧 Rated Voltage (MAX.)	125 V (実効値 rms)	
最大許容電流 及び適用電線 Rated Current (MAX.) and Applicable wires	AWG. #26	1.0 A
	AWG. #28	1.0 A
	AWG. #30	1.0 A
	AWG. #32	0.8 A
使用温度範囲 Ambient Temperature Range		-40°C ~ +85°C*1

REV.	A	B	C	D	E																			
SHEET	1-9	1-9	1-9	1-9	1-9																			
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E		変更 REVISED J2005-1671 '04/12/06 E.SUZUKI				-LEAD FREE- 製品仕様書																		
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REV.	DESCRIPTION					WRITTEN BY: E.SUZUKI	CHECKED BY: K.TOJO	APPROVED BY: M.SASAO	DATE: YR/MO/DAY 2004/02/05															
DESIGN CONTROL J						STATUS																		
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*1: 通電による温度上昇分も含む。
Including terminal temperature rise.

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[4. 性能 PERFORMANCE]

4-1. 電気的性能 ELECTRICAL PERFORMANCE

項 目 Item		条 件 Test Condition	規 格 Requirement
4-1-1	接触抵抗 Contact Resistance	コネクタを嵌合させ、開放電圧20mV 以下、 短絡電流 10mA以下にて測定する。 (JIS C5402 5.4) Mate connectors, measure by dry circuit, 20mV MAX., 10mA MAX. (JIS C5402 5.4)	20 milliohm MAX.
4-1-2	絶縁抵抗 Insulation Resistance	コネクタを嵌合させ、隣接するターミナル間及び ターミナル、アース間に、DC 500V を印加し測 定する。 (JIS C5402 5.2/MIL-STD-202 試験法 302B) Apply 500V DC between adjacent terminals or terminal and ground. (JIS C5402 5.2/MIL-STD-202 Method 302B)	100 Megohm MIN.
4-1-3	耐電圧 Dielectric Strength	コネクタを嵌合させ、隣接するターミナル間及び ターミナル、アース間に、AC250V (実効値) を 1 分間 印加する。 (JIS C5402 5.1/MIL-STD-202 試験法 301) Apply 250V AC(rms) between adjacent terminals or terminal and ground for 1 minute. (JIS C5402 5.1/MIL-STD-202 Method 301)	異常なきこと No Breakdown
4-1-4	圧着部接触抵抗 Contact Resistance on Crimped Portion	ターミナルに適合電線を圧着し、開放電圧20mV 以下、短絡電流 10mA以下にて測定する。 Crimp the applicable wire to the terminal, and measure contact resistance by dry circuit, 20mV MAX., 10mA.MAX.	5 milliohm MAX.

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4-2. 機械的性能 MECHANICAL PERFORMANCE

項 目 Item		条 件 Test Condition	規 格 Requirement	
4-2-1	挿入力 及び抜去力 Insertion and Withdrawal Force	毎分 $25 \pm 3\text{mm}$ の速さで挿入、抜去を行 う。 Insert and withdraw connectors at the speed rate of $25 \pm 3\text{mm/minute}$.	第 7 参照 Refer to paragraph 7	
4-2-2	圧着部 引張り強度 Crimping Strength	圧着されたターミナルを治具に固定し、電 線を軸方向に毎分 $25 \pm 3\text{mm}$ の速さで引張 る。 (JIS C5402 6.8) Fix the crimped terminal, apply axial pull out force on the wire at the speed rate of $25 \pm 3\text{mm/minute}$. (JIS C5402 6.8)	AWG. #26	9.8 N {1.0kgf} MIN.
			AWG. #28	9.8 N {1.0kgf} MIN.
			AWG. #30	4.9 N {0.5kgf} MIN.
			AWG. #32	3.0 N {0.3kgf} MIN.
4-2-3	ターミナル 挿入力 Terminal Insertion Force	圧着されたターミナルをハウジングに 挿入する。 Insert the crimped terminal into the housing.	4.9 N {0.5kgf} MAX.	
4-2-4	ターミナル 保持力 Terminal/ Housing Retention Force	圧着されたターミナルをハウジングに装着 し、 電線を軸方向に毎分 $25 \pm 3\text{mm}$ の速さで 引張る。 Apply axial pull out force to the terminal assembled in the housing at the speed rate of $25 \pm 3\text{mm/minute}$.	4.9 N {0.5kgf} MIN.	
4-2-5	ピン保持力 Pin Retention Force	毎分 $25 \pm 3\text{mm}$ の速さで ピンを軸方 向に 押す。 Apply axial push force at the speed rate of $25 \pm 3\text{mm/minute}$.	4.9 N {0.5kgf} MIN.	

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4-3. その他 OTHERS

項 目 Item		条 件 Test Condition	規 格 Requirement	
4-3-1	繰り返し挿抜 Repeated Insertion/ Withdrawal	1分間に10回以下の速さで挿入、抜去を30回繰り返す。 When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute.	接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-2	温度上昇 Temperature Rise	コネクタを嵌合させ、最大許容電流を通電し、コネクタの温度上昇分を測定する。 (UL 498) Carrying rated current load. (UL 498)	温度上昇 Temperature Rise	30°C MAX.
4-3-3	耐振動性 Vibration	DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な3方向に掃引割合10~55~10Hz/分全振幅 1.5mmの振動を各2時間加える。 (JIS C60068-2-6/MIL-STD-202 試験法 201) Amplitude : 1.5mm P-P Sweep time : 10-55-10 Hz in 1 minute Duration : 2 hours in each x.y.z. axes (JIS C60068-2-6/MIL-STD-202 Method 201)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			瞬 断 Discontinuity	1.0 microsecond MAX.
4-3-4	耐衝撃性 Shock	DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な6方向に490m/s ² {50G}, の衝撃を各3回加える。 (JIS C60068-2-27/MIL-STD-202 試験法213) 490m/s ² {50G}, 3 strokes in each X.Y.Z. axes. (JIS C60068-2-27 MIL-STD-202 Method 213)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			瞬 断 Discontinuity	1.0 microsecond MAX.
4-3-5	耐熱性 Heat Resistance	コネクタを嵌合させ、85±2°Cの雰囲気中に96時間放置後取出し、1~2時間室温に放置する。 (JIS C60068-2-2/MIL-STD-202 試験法108) 85±2°C, 96 hours (JIS C60068-2-2/MIL-STD-202 Method 108)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.

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-LEAD FREE-

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項 目 Item		条 件 Test Condition	規 格 Requirement	
4-3-6	耐寒性 Cold Resistance	コネクタを嵌合させ、 $-40\pm 3^{\circ}\text{C}$ の雰囲気中に96時間放置後取出し、1～2時間室温に放置する。 (JIS C60068-2-1) $-40\pm 3^{\circ}\text{C}$, 96 hours (JIS C60068-2-1)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-7	耐湿性 Humidity	コネクタを嵌合させ、 $60\pm 2^{\circ}\text{C}$ 、相対湿度90～95%の雰囲気中に96時間放置後取出し、1～2時間室温に放置する。 (JIS C60068-2-3/MIL-STD-202試験法103) Temperature : $60\pm 2^{\circ}\text{C}$ Relative Humidity : 90～95% Duration : 96 hours (JIS C60068-2-3/MIL-STD-202 Method 103)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			耐 電 圧 Dielectric Strength	4-1-3項を 満たすこと Must meet 4-1-3
			絶縁抵抗 Insulation Resistance	10 Megohm MIN.
4-3-8	温度サイクル Temperature Cycling	コネクタを嵌合させ、 -55°C に30分、 $+105^{\circ}\text{C}$ に30分 これを1サイクルとし、5サイクル繰り返す。但し、温度移行時間は5分以内とする。試験後、1～2時間室温に放置する。 (JIS C0025) 5 cycles of : a) -55°C 30minute b) $+105^{\circ}\text{C}$ 30minute (JIS C0025)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-9	塩水噴霧 Salt Spray	コネクタを嵌合させ、 $35\pm 2^{\circ}\text{C}$ にて $5\pm 1\%$ 重量比の塩水を 48 ± 4 時間噴霧し、試験後常温で水洗いした後、室温で乾燥させる。 (JIS C60068-2-11/MIL-STD-202 試験法101) 48 ± 4 hours exposure to a salt spray from the $5\pm 1\%$ solution at $35\pm 2^{\circ}\text{C}$. (JIS C60068-2-11/MIL-STD-202 Method 101)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.

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1.25mm PITCH WIRE TO BOARD CONNECTOR

-LEAD FREE-

製品仕様書

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項 目 Item		条 件 Test Condition	規 格 Requirement	
4-3-10	耐亜硫酸ガス SO ₂ Gas	コネクタを嵌合させ、40±2℃ にて 50±5ppm の亜硫酸ガス中に 24時間 放置する。 24 hours expose to 50±5ppm . SO ₂ gas at 40±2℃.	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-11	耐アンモニア 性 NH ₃ Gas	コネクタを嵌合させ、濃度28%のアンモニア 水 を入れた容器中に40分間放置する。 (1Lに対して25mLの割合) 40 minutes exposure to NH ₃ gas evaporating from 28% Ammonia solution.	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-12	半田付け性 Solderability	端子先端より0.5mm迄、及び金具先端を 245±3℃の半田に3±0.5秒浸す。 Soldering Time : 3±0.5 sec. Solder Temperature : 245±3℃ 0.5mm from terminal tip and fitting nail tip.	濡れ性 Solder Wetting	浸漬面積の 95%以上 95% of immersed area must show no voids, pin holes
4-3-13	半田耐熱性 Resistance To Solder- Ing Heat	(リフロー時) 第8項の条件を2回繰り返す。 <u>When reflowing</u> Repeat paragraph 8, condition two times.	端子ガタ、割れ等 異状なきこと No Damage	
		(手半田) 端子先端より0.5mm迄、及び金具先端を、 370～400℃の半田ゴテにて、 最大5秒 加熱する。 <u>Soldering iron method</u> Soldering time : 5 sec. MAX. Solder temperature : 370～400℃ 0.5mm from terminal tip and fitting nail tip		

() : 参考規格 Reference Standard

{ } : 参考単位 Reference Unit

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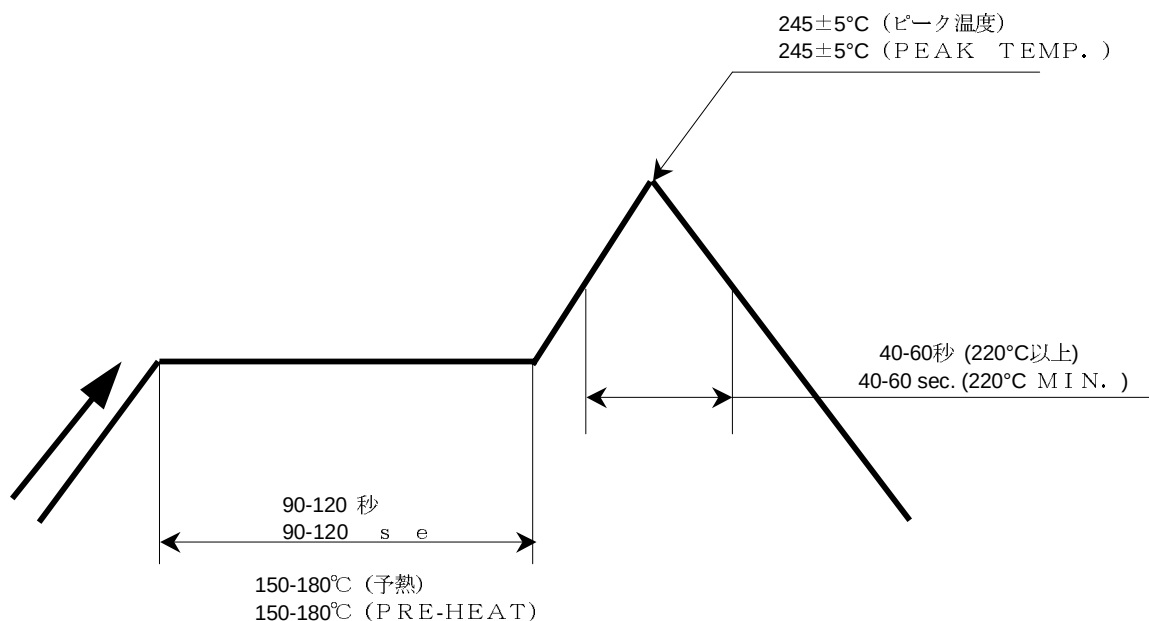
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[5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS]

図面参照 Refer to the drawing.

[6. 赤外線リフロー条件 INFRARED REFLOW CONDITION]



温度条件グラフ
(温度は基板パターン面)
TEMPERATURE CONDITION GRAPH
(TEMPERATURE ON THE SURFACE OF P.C.BOARD PATTERN)

注記 ; 本リフロー条件に関しては、リフロー装置及び基板などにより条件が異なりますので、
事前にリフロー評価の確認をお願い致します。
また吸湿などの前処理は行わないで下さい。

NOTE ; Please check the reflow soldering condition by your own devices beforehand.
Because the condition changes by the soldering devices, P.C.Boards, and so on.
No moisture treatment before reflow process.

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[7. 挿入力及び抜去力 INSERTION / WITHDRAWAL FORCE]

極数 No. of CKT.	単位 Unit	挿入力 (最大値) Insertion force (MAX.)			抜去力 (最小値) Withdrawal force (MIN.)		
		初回 1st	6回目 6th	30回目 30th	初回 1st	6回目 6th	30回目 30th
2	N { kgf }	19.6 { 2.0 }	17.6 { 1.8 }	15.6 { 1.6 }	2.8 { 0.28 }	2.3 { 0.23 }	1.8 { 0.18 }
3	N { kgf }	24.5 { 2.5 }	22.5 { 2.3 }	20.5 { 2.1 }	3.0 { 0.30 }	2.5 { 0.25 }	2.0 { 0.20 }
4	N { kgf }	29.4 { 3.0 }	27.4 { 2.8 }	25.4 { 2.6 }	3.3 { 0.33 }	2.8 { 0.28 }	2.3 { 0.23 }
5	N { kgf }	34.3 { 3.5 }	32.3 { 3.3 }	30.3 { 3.1 }	3.8 { 0.38 }	3.3 { 0.33 }	2.8 { 0.28 }
6	N { kgf }	39.2 { 4.0 }	37.2 { 3.8 }	35.2 { 3.6 }	4.3 { 0.43 }	3.8 { 0.38 }	3.3 { 0.33 }
7	N { kgf }	44.1 { 4.5 }	42.1 { 4.3 }	40.1 { 4.1 }	4.7 { 0.48 }	4.3 { 0.43 }	3.8 { 0.38 }
8	N { kgf }	49.0 { 5.0 }	47.0 { 4.8 }	45.0 { 4.6 }	5.2 { 0.53 }	4.7 { 0.48 }	4.3 { 0.43 }
9	N { kgf }	53.9 { 5.5 }	51.9 { 5.3 }	49.9 { 5.1 }	5.5 { 0.56 }	5.0 { 0.51 }	4.5 { 0.46 }
10	N { kgf }	58.8 { 6.0 }	56.8 { 5.8 }	54.8 { 5.6 }	5.8 { 0.59 }	5.3 { 0.54 }	4.8 { 0.49 }
11	N { kgf }	63.7 { 6.5 }	61.7 { 6.3 }	59.7 { 6.1 }	6.1 { 0.62 }	5.6 { 0.57 }	5.1 { 0.52 }
12	N { kgf }	68.6 { 7.0 }	66.6 { 6.8 }	64.6 { 6.6 }	6.4 { 0.65 }	5.9 { 0.60 }	5.4 { 0.55 }
13	N { kgf }	73.5 { 7.5 }	71.5 { 7.3 }	69.5 { 7.1 }	6.7 { 0.68 }	6.2 { 0.63 }	5.7 { 0.58 }
14	N { kgf }	78.4 { 8.0 }	76.4 { 7.8 }	74.4 { 7.6 }	7.0 { 0.71 }	6.5 { 0.66 }	6.0 { 0.61 }
15	N { kgf }	83.3 { 8.5 }	81.3 { 8.3 }	79.3 { 8.1 }	7.3 { 0.74 }	6.8 { 0.69 }	6.3 { 0.64 }

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EN-37-1(019)



PRODUCT SPECIFICATION

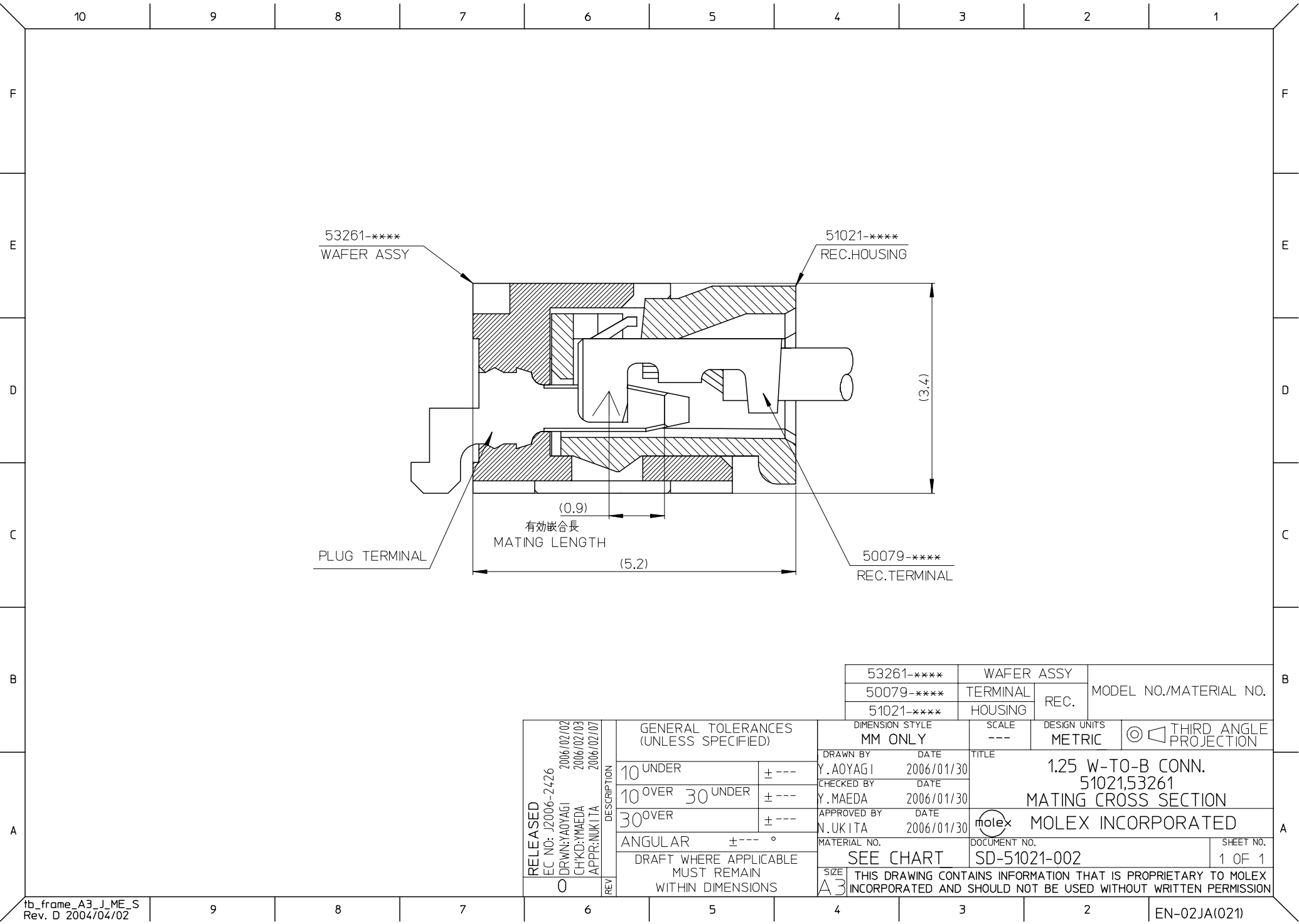


LANGUAGE

JAPANESE
ENGLISH

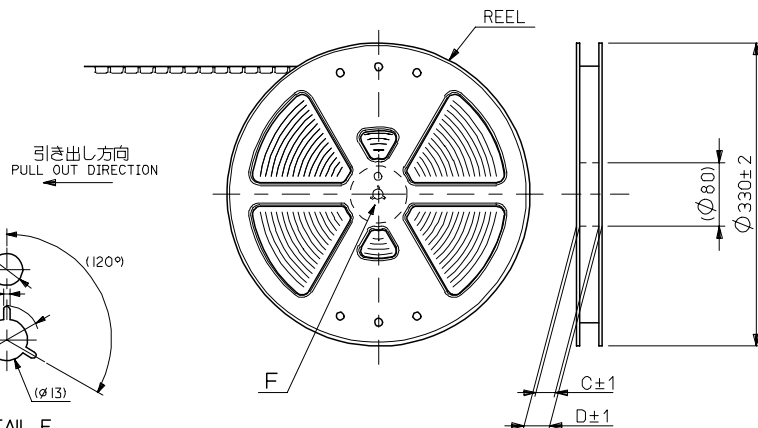
REV.	REV. RECORD	DATE	EC NO.	WRTTN:	CH'K:
A	RELEASED	'04/02/05	J2004-2276	E.SUZUKI	K.TOJO
B	REVISED	'04/03/10	J2004-3002	E.SUZUKI	K.TOJO
C	REVISED	'04/03/29	J2004-3401	E.SUZUKI	K.TOJO
D	REVISED	'04/07/21	J2005-0243	N.AIDA	K.TOJO
E	REVISED	'04/12/06	J2005-1671	E.SUZUKI	K.TOJO

	REVISE ON PC ONLY		TITLE: 1.25mm PITCH WIRE TO BOARD CONNECTOR -LEAD FREE-製品仕様書		
	E	SEE SHEET 1 OF 9			
	REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DOCUMENT NUMBER PS-51021-024				FILE NAME PS51021024.DOC	SHEET 10 OF 9
EN-37-1(019)					

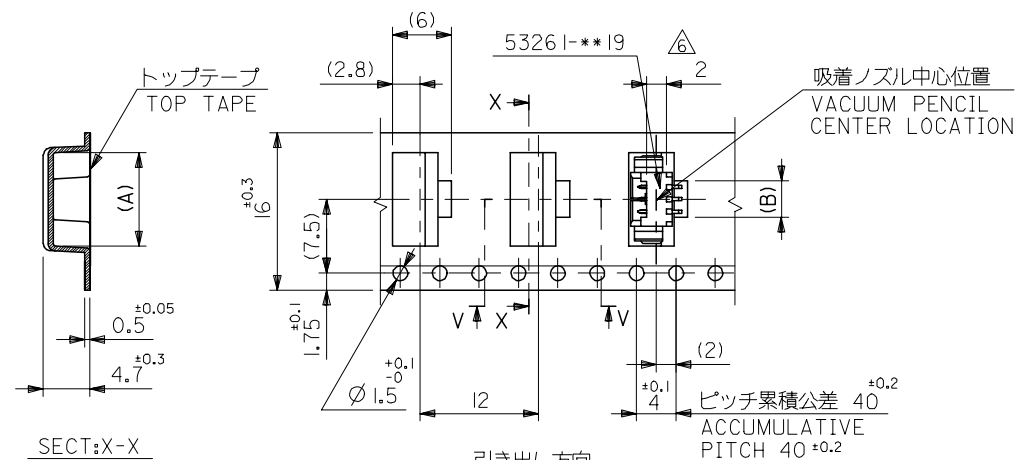


53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

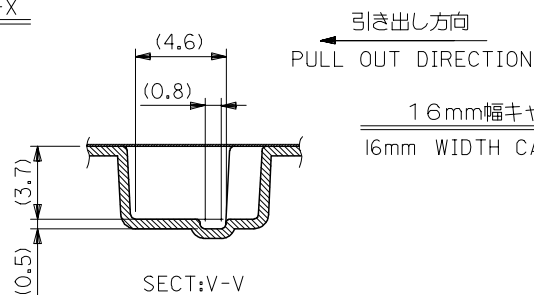
RELEASED EC NO: J2006-2426 DRWN:YAOYAGI 2006/02/02 CHKD:YMAEDA 2006/02/03 APPR:NUKITA 2006/02/07 REV 0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	Y.AOYAGI	2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
		10 OVER 30 UNDER	± ---	Y.MAEDA	2006/01/30					
		30 OVER	± ---	N.UKITA	2006/01/30	MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-51021-002		1 OF 1		
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



DETAIL F



SECT:X-X



SECT:V-V

16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

注記 NOTES

1. 53261-**-19 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-024

2. 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH

トップテープリーダー部 TOP TAPE LEADER PART
トップテープ未接着部 TOP TAPE NON-BONDED PART

175 ±25 25 ±5

引き出し方向
PULL OUT DIRECTION



4. 材料 (MATERIAL)

キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)

トップテープ (TOP TAPE): PET, PE, PEF

リール (REEL): ポリスチレン (PS) <リサイクル材含む>

POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>

△ コネクタ、ハウジング平面部

CONNECTOR, HOUSING FLAT AREA

6. 本製品は 53261-**-90 の鉛フリー品である。

THIS PRODUCT IS LEAD FREE OF 53261-**-90

7. ELV 及び RoHS 適合品

ELV AND RoHS COMPLIANT

MODEL NO. 53261-**-71

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER ±0.2

10 OVER 30 UNDER ±0.25

30 OVER ±0.3

ANGULAR ±3 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY DATE

H. SHIMABUKUR '04/02/06

CHECKED BY DATE

K. TOJO '04/02/06

APPROVED BY DATE

M. SASAO '04/02/06

MATERIAL NO.

SEE CHART

SIZE A3

SCALE

TITLE

1.25 W/B CONN WAFER ASSY
FOR SMT EMBSTP PKG

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

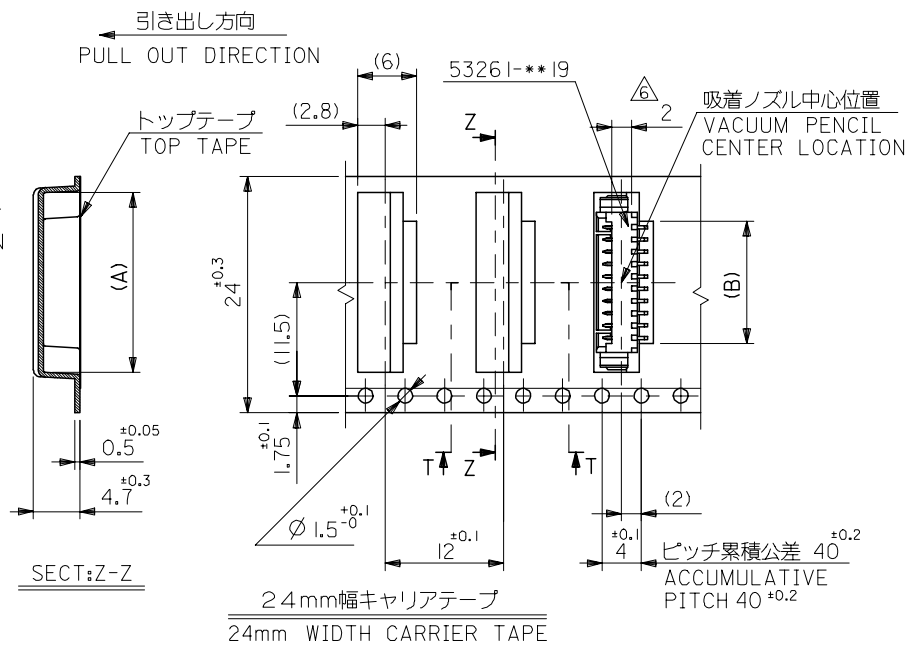
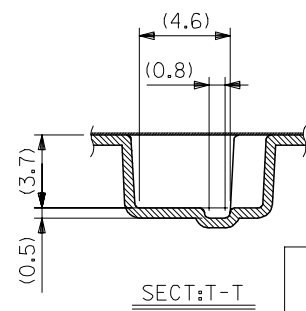
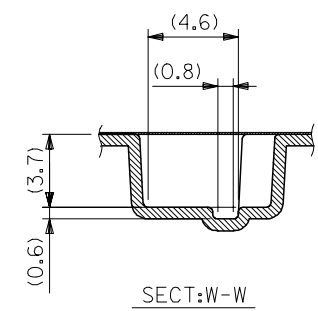
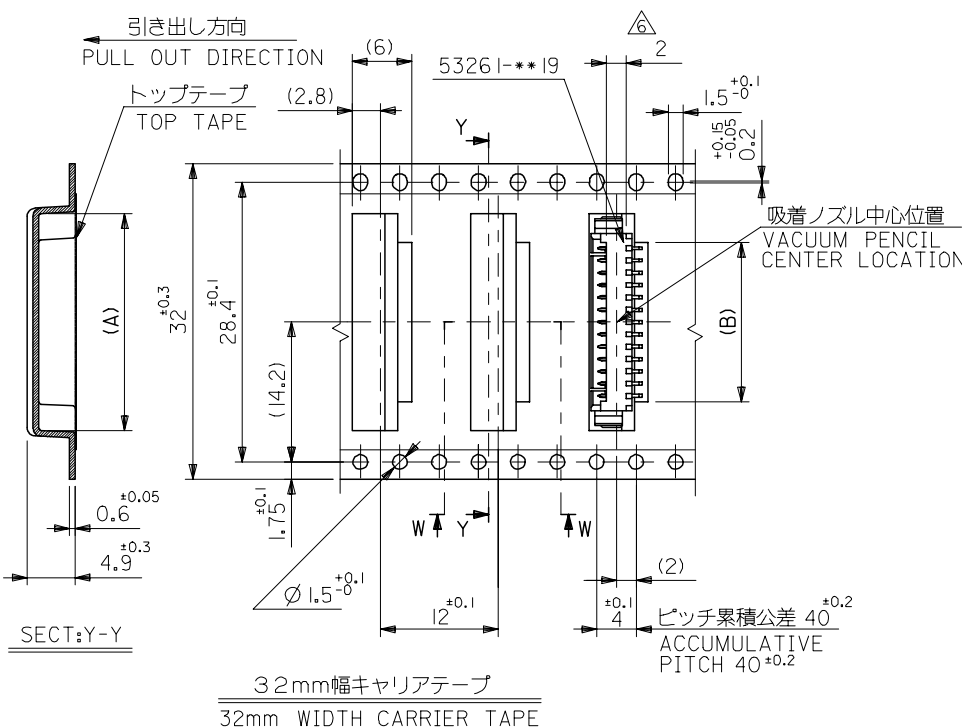
MOLEX INCORPORATED

DOCUMENT NO.

SD-53261-023

SHEET NO.

1 OF 3



32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
			13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
24	29.4	25.4	6.2	12	-0571	5
			4.95	10.75	53261-0471	4

REVISED EC NO: J2008-0056 DRW:KSAI T001 CHKD:THARUYAMA APPR:NUKI TA		DESCRIPTION 2007/07/31 2007/07/31 2007/08/10		MODEL NO.		53261-**-71		キャリアテープ幅 CARRIER TAPE WIDTH		D	C	B	A	MATERIAL. NO.		種数 CKT.	
				GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE MM ONLY				SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
				10 UNDER		±0.2		DRAWN BY H. SHIMABUKUR		DATE '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG					
				10 OVER 30 UNDER		±0.25		CHECKED BY K. TOJO		DATE '04/02/06							
				30 OVER		±0.3		APPROVED BY M. SASAO		DATE '04/02/06							
ANGULAR		±3 °		MATERIAL NO.				DOCUMENT NO.						SHEET NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		SEE CHART						SD-53261-023						2 OF 3	
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